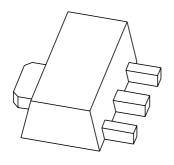
DISCRETE SEMICONDUCTORS

DATA SHEET



BST50; BST51; BST52 NPN Darlington transistors

Product specification Supersedes data of 2001 Feb 20

2004 Dec 09





NPN Darlington transistors

BST50; **BST51**; **BST52**

FEATURES

- High current (max. 0.5 A)
- Low voltage (max. 80 V)
- Integrated diode and resistor.

APPLICATIONS

- Industrial switching applications such as:
 - Print hammer
 - Solenoid
 - Relay and lamp driving.

DESCRIPTION

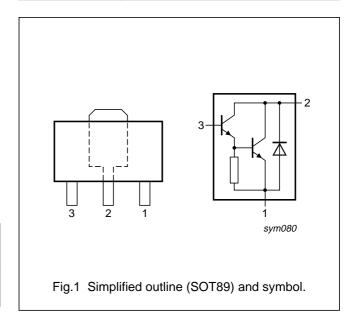
NPN Darlington transistor in a SOT89 plastic package. PNP complements: BST60, BST61 and BST62.

MARKING

TYPE NUMBER	MARKING CODE
BST50	AS1
BST51	AS2
BST52	AS3

PINNING

PIN	DESCRIPTION	
1	emitter	
2	collector	
3	base	



ORDERING INFORMATION

TYPE NUMBER	PACKAGE			
I TPE NUMBER	NAME	DESCRIPTION	VERSION	
BST50	SC-62	plastic surface mounted package; collector pad for good heat	SOT89	
BST51		transfer; 3 leads		
BST52				

NPN Darlington transistors

BST50; BST51; BST52

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter			
	BST50		_	60	V
	BST51		_	80	V
	BST52		_	90	V
V _{CES}	collector-emitter voltage	V _{BE} = 0 V			
	BST50		_	45	V
	BST51		_	60	V
	BST52		_	80	V
V _{EBO}	emitter-base voltage	open collector	_	5	V
I _C	collector current (DC)		_	1	Α
I _{CM}	peak collector current		_	2	Α
I _B	base current (DC)		_	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	1.3	W
Tj	junction temperature		_	150	°C
T _{amb}	ambient temperature		–65	+150	°C
T _{stg}	storage temperature		-65	+150	°C

Note

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	96	K/W
R _{th(j-s)}	thermal resistance from junction to soldering point		16	K/W

Note

Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm².
 For other mounting conditions, see "Thermal considerations for SOT89 in the General Part of associated Handbook".

^{1.} Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm². For other mounting conditions, see "Thermal considerations for SOT89 in the General Part of associated Handbook".

NPN Darlington transistors

BST50; BST51; BST52

CHARACTERISTICS

 T_{amb} = 25 $^{\circ}C$ unless otherwise specified.

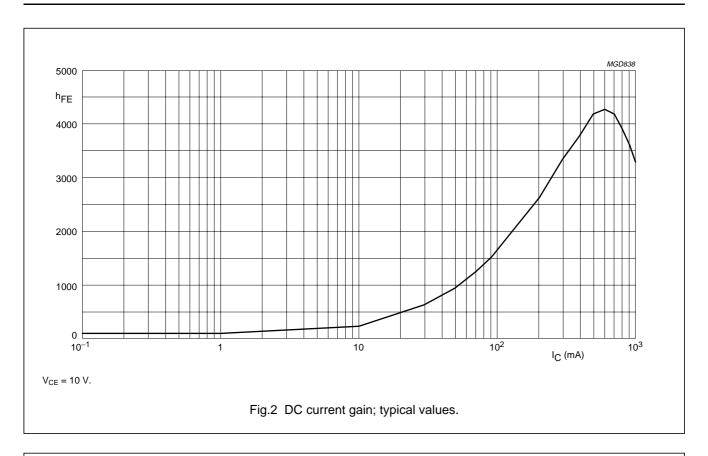
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CES}	collector-emitter cut-off current					
	BST50	V _{BE} = 0 V; V _{CE} = 45 V	_	-	50	nA
	BST51	V _{BE} = 0 V; V _{CE} = 60 V	_	_	50	nA
	BST52	V _{BE} = 0 V; V _{CE} = 80 V	_	-	50	nA
I _{EBO}	emitter-base cut-off current	I _C = 0 A; V _{EB} = 4 V	_	_	50	nA
h _{FE}	DC current gain	V _{CE} = 10 V; note 1; (see Fig.2)				
		I _C = 150 mA	1000	-	_	
		I _C = 500 mA	2000	-	_	
V _{CEsat}	collector-emitter saturation	I _C = 500 mA; I _B = 0.5 mA	_	_	1.3	V
	voltage	$I_C = 500 \text{ mA}; I_B = 0.5 \text{ mA};$ $T_j = 150 \text{ °C}$	_	_	1.3	V
V _{BEsat}	base-emitter saturation voltage	I _C = 500 mA; I _B = 0.5 mA	_	_	1.9	V
f _T	transition frequency	I _C = 500 mA; V _{CE} = 5 V; f = 100 MHz	_	200	_	MHz
Switching ti	Switching times (between 10% and 90% levels); (see Fig.3)					
t _{on}	turn-on time	I _{Con} = 500 mA; I _{Bon} = 0.5 mA;	_	400	_	ns
t _{off}	turn-off time	$I_{Boff} = -0.5 \text{ mA}$	_	1500	_	ns

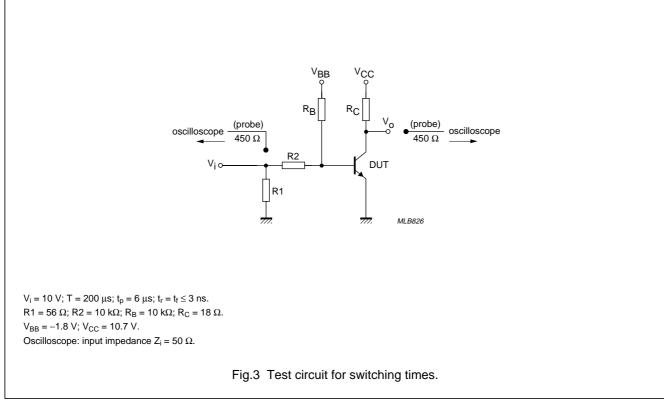
Note

1. Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

NPN Darlington transistors

BST50; BST51; BST52





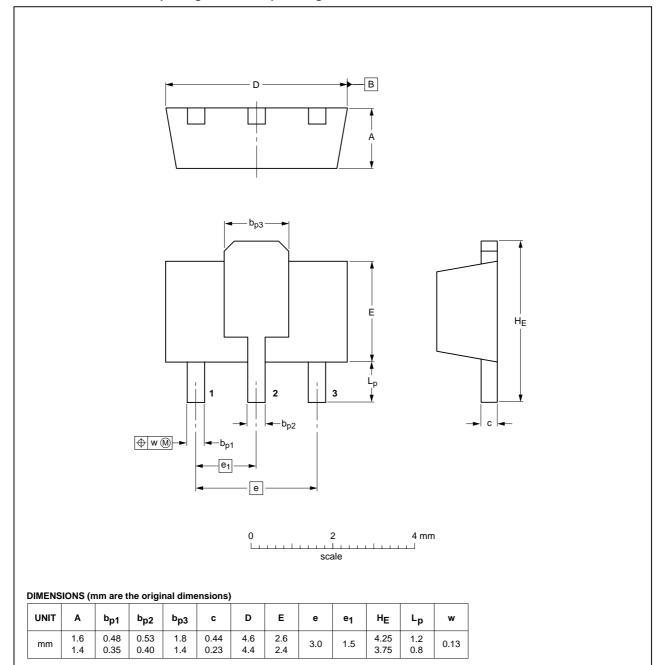
NPN Darlington transistors

BST50; BST51; BST52

PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 3 leads

SOT89



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT89		TO-243	SC-62			99-09-13 04-08-03

NPN Darlington transistors

BST50; BST51; BST52

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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